

Features

- Temperature ranges
 - Industrial: -40 °C to 85 °C
 - Automotive-A: -40 °C to 85 °C
- Pin-and function-compatible with CY7C1021CV33
- High speed
 - $t_{AA} = 10 \text{ ns}$
- Low active power
 - $I_{CC} = 60 \text{ mA @ } 10 \text{ ns}$
- Low CMOS standby power
 - $I_{SB2} = 3 \text{ mA}$
- 2.0 V data retention
- Automatic power-down when deselected
- CMOS for optimum speed/power
- Independent control of upper and lower bits
- Available in Pb-free 44-pin 400-Mil wide molded SOJ, 44-pin TSOP II and 48-ball VFBGA packages

Functional Description

The CY7C1021DV33 is a high-performance CMOS static RAM organized as 65,536 words by 16 bits. This device has an automatic power-down feature that significantly reduces power consumption when deselected.

Writing to the device is accomplished by taking Chip Enable (\overline{CE}) and Write Enable (WE) inputs LOW. If Byte Low Enable (BLE) is LOW, then data from I/O pins (I/O₀ through I/O₇), is written into the location specified on the address pins (A₀ through A₁₅). If Byte High Enable (BHE) is LOW, then data from I/O pins (I/O₈ through I/O₁₅) is written into the location specified on the address pins (A₀ through A₁₅).

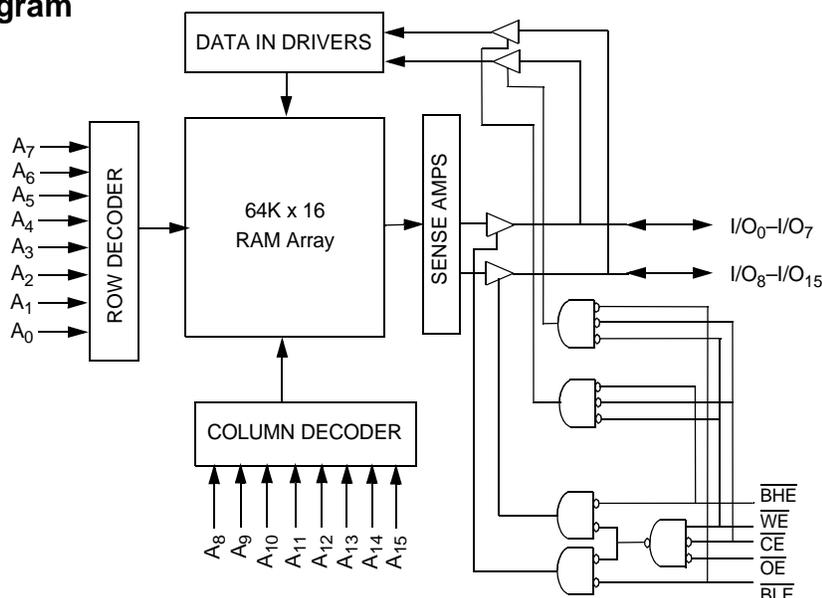
Reading from the device is accomplished by taking Chip Enable (\overline{CE}) and Output Enable (\overline{OE}) LOW while forcing the Write Enable (WE) HIGH. If Byte Low Enable (BLE) is LOW, then data from the memory location specified by the address pins will appear on I/O₀ to I/O₇. If Byte High Enable (BHE) is LOW, then data from memory will appear on I/O₈ to I/O₁₅. See the truth table at the end of this data sheet for a complete description of Read and Write modes.

The input/output pins (I/O₀ through I/O₁₅) are placed in a high-impedance state when the device is deselected (\overline{CE} HIGH), the outputs are disabled (\overline{OE} HIGH), the BHE and BLE are disabled (BHE, BLE HIGH), or during a Write operation (\overline{CE} LOW, and WE LOW).

The CY7C1021DV33 is available in Pb-free 44-pin 400-Mil wide Molded SOJ, 44-pin TSOP II and 48-ball VFBGA packages.

For a complete list of related resources, [click here](#).

Logic Block Diagram



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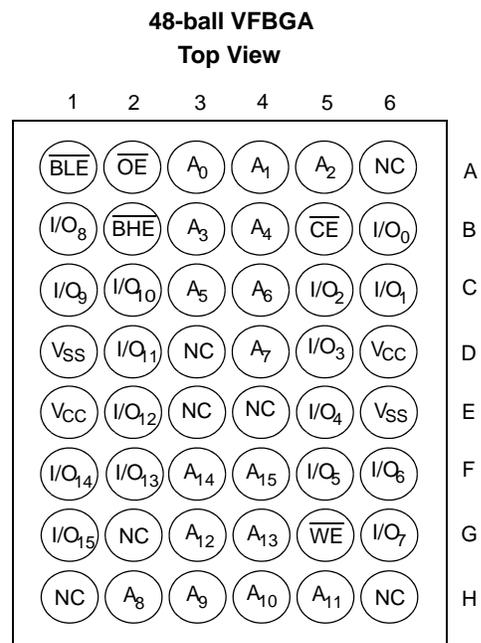
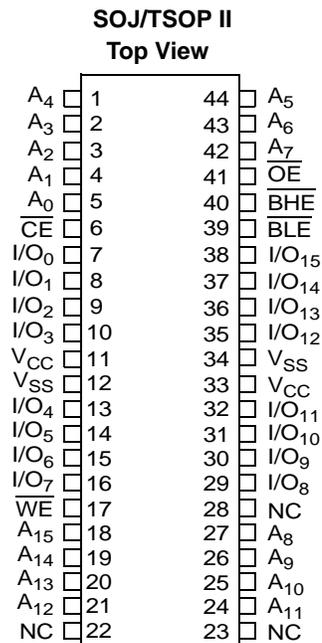
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Selection Guide

Description	-10 (Industrial / Automotive-A)	Unit
Maximum access time	10	ns
Maximum operating current	60	mA
Maximum CMOS standby current	3	mA

Pin Configurations

SOJ, TSOP II and VFBGA pinouts are as follows. [1]



Note

1. NC pins are not connected on the die.

Maximum Ratings

Exceeding maximum ratings may impair the useful life of the device. These user guidelines are not tested.

- Storage temperature -65 °C to +150 °C
- Ambient temperature with power applied -55 °C to +125 °C
- Supply voltage on V_{CC} to Relative GND [2] -0.3 V to +4.6 V
- DC Voltage applied to outputs in high Z State [2] -0.3 V to V_{CC} + 0.3 V
- DC input voltage [2] -0.3 V to V_{CC} + 0.3 V

- Current into outputs (LOW) 20 mA
- Static discharge voltage (per MIL-STD-883, method 3015) > 2001 V
- Latch-up current > 200 mA

Operating Range

Range	Ambient Temperature	V _{CC}	Speed
Industrial	-40 °C to +85 °C	3.3 V ± 0.3 V	10 ns
Automotive-A	-40 °C to +85 °C		10 ns

Electrical Characteristics

Over the Operating Range

DC Electrical Characteristics

Over the Operating Range

Parameter	Description	Test Conditions	-10 (Industrial / Automotive-A)		Unit	
			Min	Max		
V _{OH}	Output HIGH voltage	V _{CC} = Min, I _{OH} = -4.0 mA	2.4	-	V	
V _{OL}	Output LOW voltage	V _{CC} = Min, I _{OL} = 8.0 mA	-	0.4	V	
V _{IH}	Input HIGH voltage		2.0	V _{CC} + 0.3	V	
V _{IL}	Input LOW voltage [2]		-0.3	0.8	V	
I _{Ix}	Input leakage current	GND ≤ V _I ≤ V _{CC}	-1	+1	µA	
I _{Oz}	Output leakage current	GND ≤ V _I ≤ V _{CC} , Output Disabled	-1	+1	µA	
I _{CC}	V _{CC} operating supply current	V _{CC} = Max, I _{OUT} = 0 mA, f = f _{MAX} = 1/t _{RC}	100 MHz	-	60	mA
			83 MHz	-	55	mA
			66 MHz	-	45	mA
			40 MHz	-	30	mA
I _{SB1}	Automatic CE Power-Down Current – TTL Inputs	Max V _{CC} , $\overline{CE} \geq V_{IH}$, V _{IN} ≥ V _{IH} or V _{IN} ≤ V _{IL} , f = f _{MAX}	-	10	mA	
I _{SB2}	Automatic CE Power-Down Current – CMOS Inputs	Max V _{CC} , $\overline{CE} \geq V_{CC} - 0.3 V$, V _{IN} ≥ V _{CC} - 0.3 V or V _{IN} ≤ 0.3 V, f = 0	-	3	mA	

Note

2. V_{IL(min)} = -2.0 V and V_{IH(max)} = V_{CC} + 1 V for pulse durations of less than 5 ns.

Capacitance

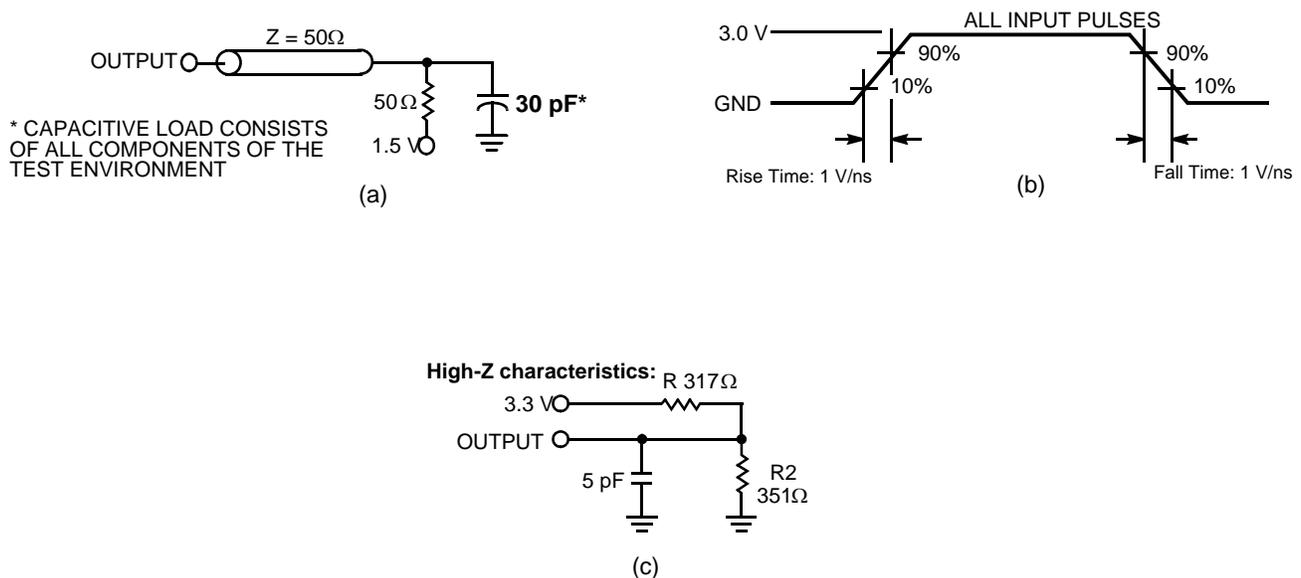
Parameter ^[3]	Description	Test Conditions	Max	Unit
C _{IN}	Input capacitance	T _A = 25 °C, f = 1 MHz, V _{CC} = 3.3 V	8	pF
C _{OUT}	Output capacitance		8	pF

Thermal Resistance

Parameter ^[3]	Description	Test Conditions	SOJ	TSOP II	VFBGA	Unit
Θ _{JA}	Thermal resistance (junction to ambient)	Still Air, soldered on a 3 x 4.5 inch, four-layer printed circuit board	59.52	53.91	36	°C/W
Θ _{JC}	Thermal resistance (junction to case)		36.75	21.24	9	°C/W

AC Test Loads and Waveforms

Figure 1. AC Test Loads and Waveforms ^[4]



Notes

- 3. Tested initially and after any design or process changes that may affect these parameters.
- 4. AC characteristics (except High Z) are tested using the load conditions shown in Figure 1 (a). High Z characteristics are tested for all speeds using the test load shown in Figure 1 (c).

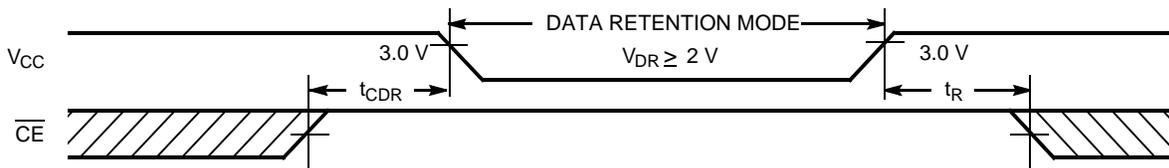
Data Retention Characteristics

Over the Operating Range

Parameter	Description	Conditions	Min	Max	Unit
V_{DR}	V_{CC} for data retention		2	–	V
I_{CCDR}	Data retention current	$V_{CC} = V_{DR} = 2.0\text{ V}$, $\overline{CE} \geq V_{CC} - 0.3\text{ V}$, $V_{IN} \geq V_{CC} - 0.3\text{ V}$ or $V_{IN} \leq 0.3\text{ V}$	–	3	mA
$t_{CDR}^{[5]}$	Chip deselect to data retention time		0	–	ns
$t_R^{[6]}$	Operation recovery time		t_{RC}	–	ns

Data Retention Waveform

Figure 2. Data Retention Waveform



Notes

5. Tested initially and after any design or process changes that may affect these parameters.
6. Full device operation requires linear V_{CC} ramp from V_{DR} to $V_{CC(min)} \geq 50\ \mu\text{s}$ or stable at $V_{CC(min)} \geq 50\ \mu\text{s}$.

Switching Characteristics

Over the Operating Range

Parameter ^[7]	Description	-10 (Industrial / Automotive-A)		Unit
		Min	Max	
Read Cycle				
$t_{power}^{[8]}$	V_{CC} (typical) to the first access	100	–	μ s
t_{RC}	Read cycle time	10	–	ns
t_{AA}	Address to data valid	–	10	ns
t_{OHA}	Data hold from address change	3	–	ns
t_{ACE}	\overline{CE} LOW to data valid	–	10	ns
t_{DOE}	\overline{OE} LOW to data valid	–	5	ns
t_{LZOE}	\overline{OE} LOW to low Z ^[9]	0	–	ns
t_{HZOE}	\overline{OE} HIGH to high Z ^[9, 10]	–	5	ns
t_{LZCE}	\overline{CE} LOW to low Z ^[9]	3	–	ns
t_{HZCE}	\overline{CE} HIGH to high Z ^[9, 10]	–	5	ns
$t_{PU}^{[11]}$	\overline{CE} LOW to power-up	0	–	ns
$t_{PD}^{[11]}$	\overline{CE} HIGH to power-down	–	10	ns
t_{DBE}	Byte Enable to data valid	–	5	ns
t_{LZBE}	Byte Enable to low Z	0	–	ns
t_{HZBE}	Byte Disable to high Z	–	6	ns
Write Cycle ^[12, 13]				
t_{WC}	Write cycle time	10	–	ns
t_{SCE}	\overline{CE} LOW to write end	8	–	ns
t_{AW}	Address set-up to write end	8	–	ns
t_{HA}	Address hold from write end	0	–	ns
t_{SA}	Address set-up to write start	0	–	ns
t_{PWE}	\overline{WE} pulse width	7	–	ns
t_{SD}	Data set-up to write end	5	–	ns
t_{HD}	Data hold from write end	0	–	ns
t_{LZWE}	\overline{WE} HIGH to low Z ^[9]	3	–	ns
t_{HZWE}	\overline{WE} LOW to high Z ^[9, 10]	–	5	ns
t_{BW}	Byte enable to end of write	7	–	ns

Notes

7. Test conditions assume signal transition time of 3 ns or less, timing reference levels of 1.5 V, input pulse levels of 0 to 3.0 V.
8. t_{POWER} gives the minimum amount of time that the power supply should be at typical V_{CC} values until the first memory access can be performed.
9. At any given temperature and voltage condition, t_{HZCE} is less than t_{LZCE} , t_{HZOE} is less than t_{LZOE} , and t_{HZWE} is less than t_{LZWE} for any given device.
10. t_{HZOE} , t_{HZBE} , t_{HZCE} , and t_{HZWE} are specified with a load capacitance of 5 pF as in (c) of [Figure 1 on page 5](#). Transition is measured when the outputs enter a high impedance state.
11. This parameter is guaranteed by design and is not tested.
12. The internal Write time of the memory is defined by the overlap of \overline{CE} LOW, \overline{WE} LOW and $\overline{BHE}/\overline{BLE}$ LOW. \overline{CE} , \overline{WE} and $\overline{BHE}/\overline{BLE}$ must be LOW to initiate a Write and the transition of these signals can terminate the Write. The input data set-up and hold timing should be referenced to the leading edge of the signal that terminates the Write.
13. The minimum write pulse width for Write Cycle No. 3 (\overline{WE} Controlled, \overline{OE} LOW) should be equal to the sum of t_{SD} and t_{HZWE} .

Switching Waveforms

Figure 3. Read Cycle No. 1 (Address Transition Controlled) [14, 15]

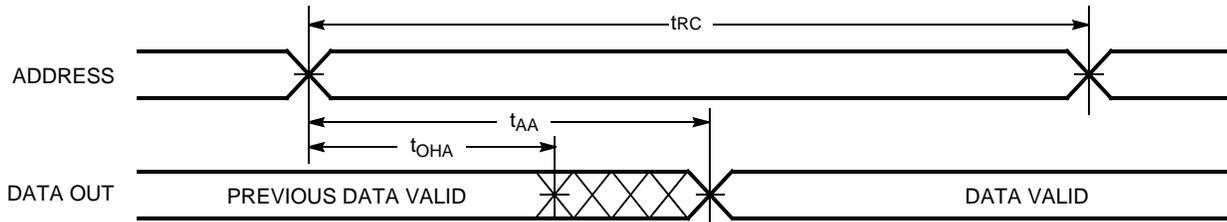
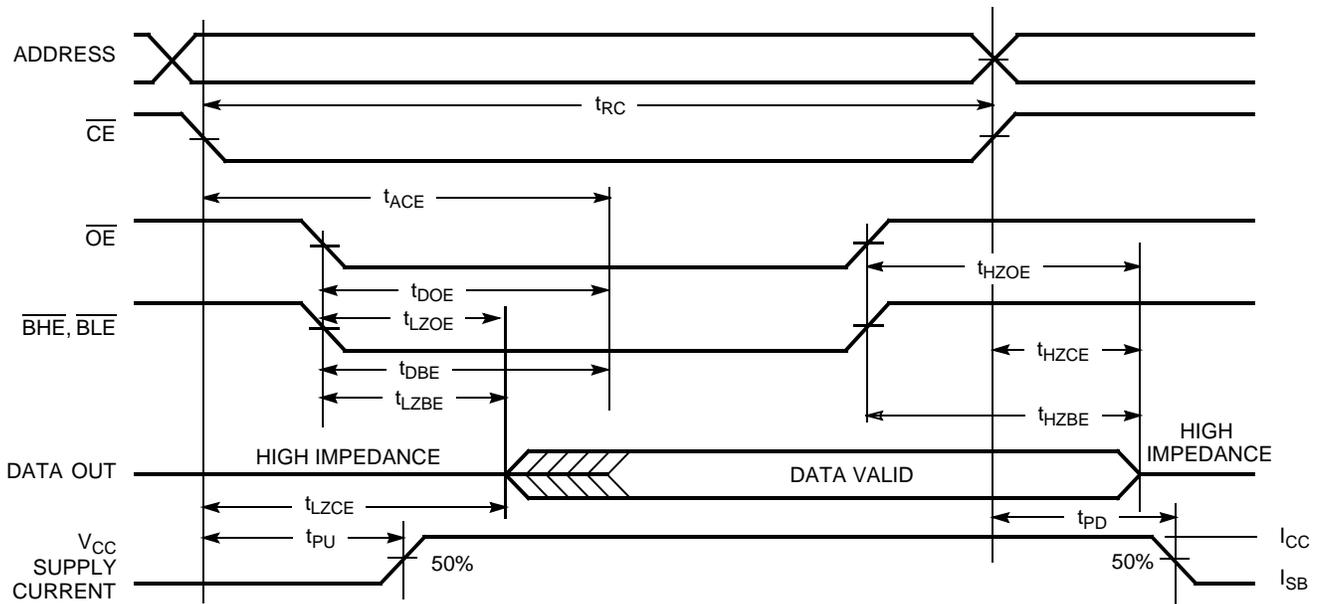


Figure 4. Read Cycle No. 2 (\overline{OE} Controlled) [15, 16]



Notes

- 14. Device is continuously selected. \overline{OE} , \overline{CE} , \overline{BHE} and/or \overline{BLE} = V_{IL} .
- 15. \overline{WE} is HIGH for Read cycle.
- 16. Address valid prior to or coincident with \overline{CE} transition LOW.

Switching Waveforms (continued)

Figure 5. Write Cycle No. 1 ($\overline{\text{CE}}$ Controlled) [17, 18]

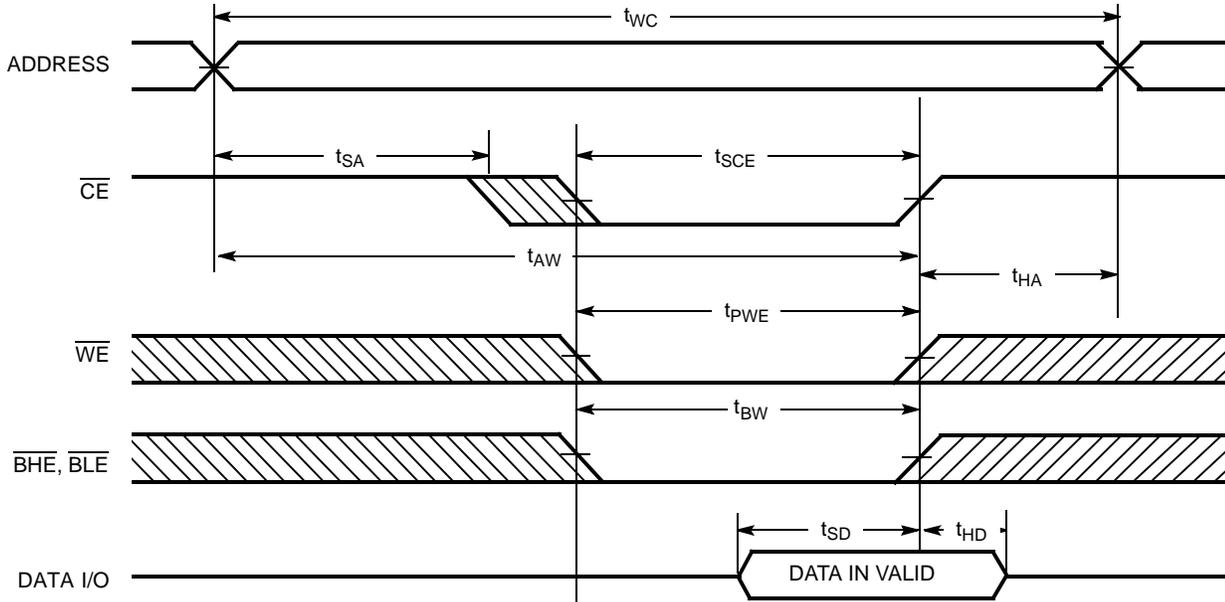
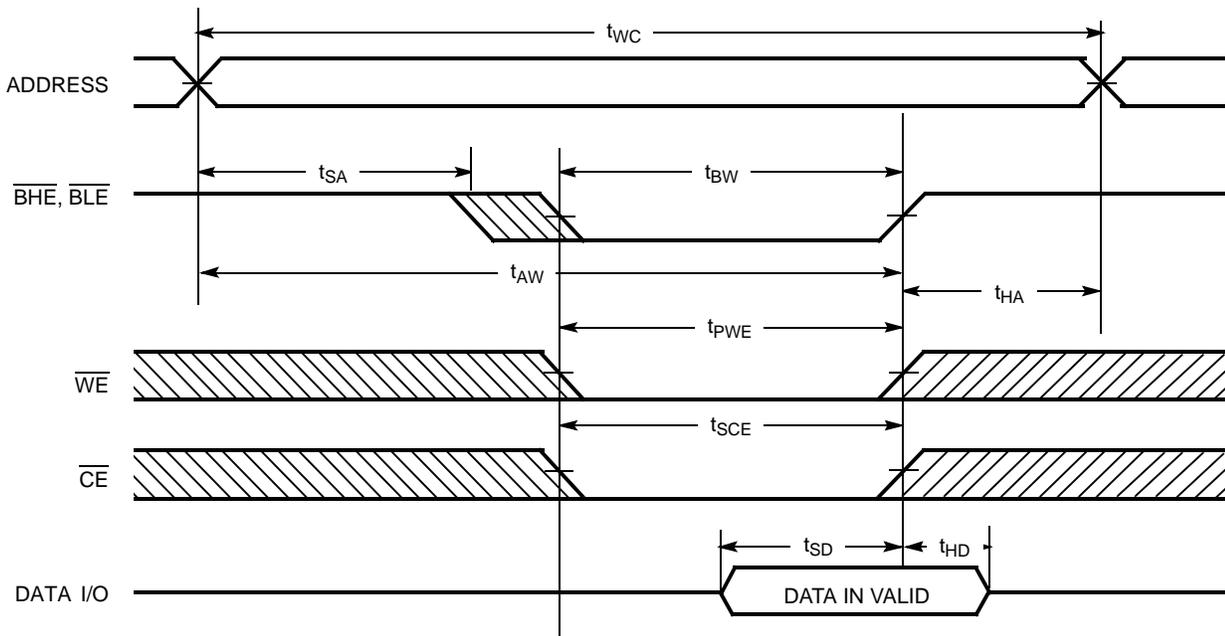


Figure 6. Write Cycle No. 2 ($\overline{\text{BLE}}$ or $\overline{\text{BHE}}$ Controlled)



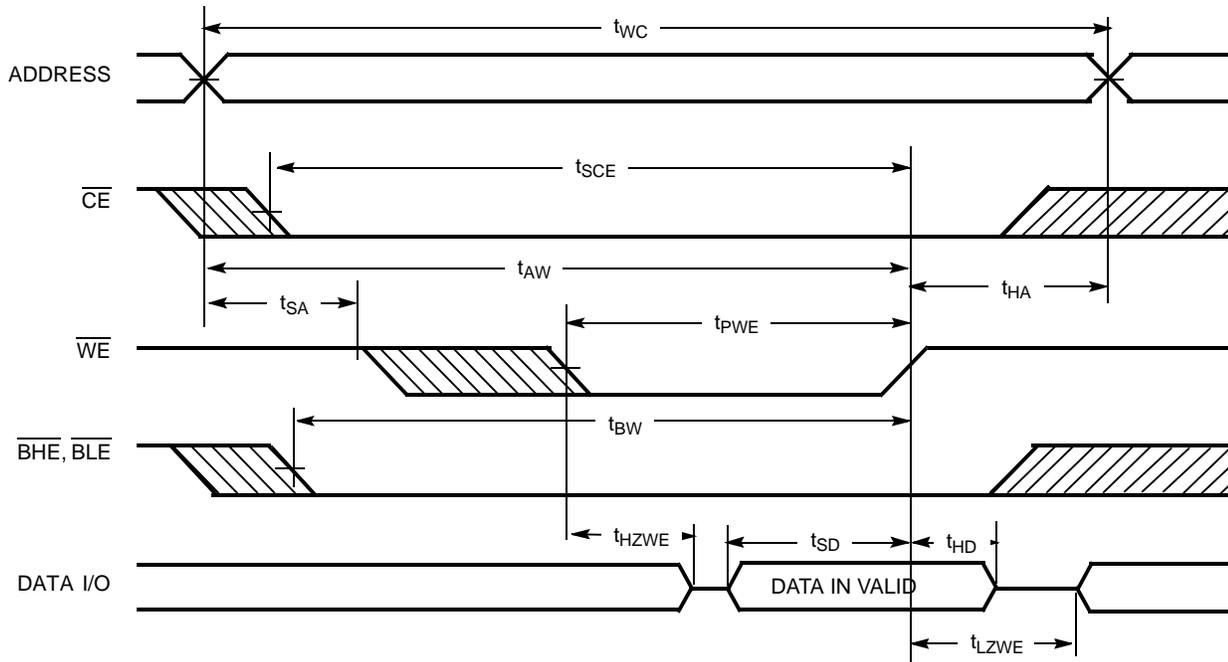
Notes

17. Data I/O is high impedance if $\overline{\text{OE}}$ or $\overline{\text{BHE}}$ and/or $\overline{\text{BLE}} = V_{IH}$.

18. If $\overline{\text{CE}}$ goes HIGH simultaneously with $\overline{\text{WE}}$ going HIGH, the output remains in a high-impedance state.

Switching Waveforms (continued)

Figure 7. Write Cycle No. 3 (\overline{WE} Controlled, \overline{OE} LOW)^[19]



Note

19. The minimum write pulse width should be equal to the sum of t_{SD} and t_{HZWE} .

Truth Table

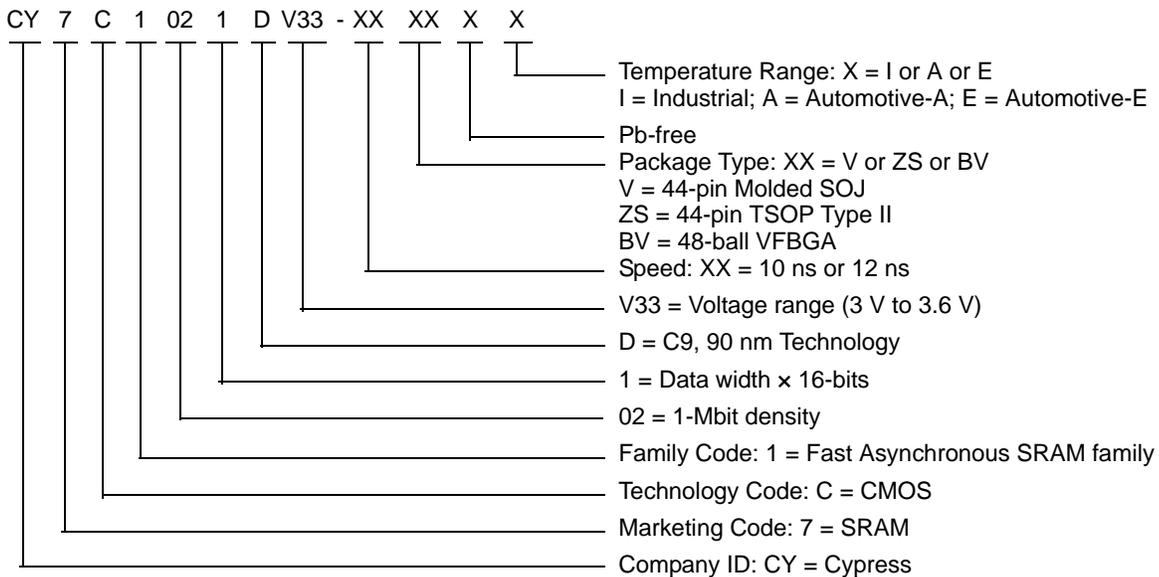
\overline{CE}	\overline{OE}	\overline{WE}	\overline{BLE}	\overline{BHE}	I/O ₀ -I/O ₇	I/O ₈ -I/O ₁₅	Mode	Power
H	X	X	X	X	High-Z	High-Z	Power-down	Standby (I _{SB})
L	L	H	L	L	Data Out	Data Out	Read – All bits	Active (I _{CC})
			L	H	Data Out	High-Z	Read – Lower bits only	Active (I _{CC})
			H	L	High-Z	Data Out	Read – Upper bits only	Active (I _{CC})
L	X	L	L	L	Data In	Data In	Write – All bits	Active (I _{CC})
			L	H	Data In	High-Z	Write – Lower bits only	Active (I _{CC})
			H	L	High-Z	Data In	Write – Upper bits only	Active (I _{CC})
L	H	H	X	X	High-Z	High-Z	Selected, outputs disabled	Active (I _{CC})
L	X	X	H	H	High-Z	High-Z	Selected, outputs disabled	Active (I _{CC})

Ordering Information

Speed (ns)	Ordering Code	Package Diagram	Package Type	Operating Range
10	CY7C1021DV33-10VXI	51-85082	44-pin (400-Mil) Molded SOJ (Pb-free)	Industrial
	CY7C1021DV33-10ZSXI	51-85087	44-pin TSOP Type II (Pb-free)	
	CY7C1021DV33-10BVXI	51-85150	48-ball VFBGA (Pb-free)	
10	CY7C1021DV33-10ZSXA	51-85087	44-pin TSOP Type II (Pb-free)	Automotive-A

Please contact your local Cypress sales representative for availability of these parts.

Ordering Code Definitions



Package Diagrams

Figure 8. 44-pin SOJ (400 Mils) V44.4 Package Outline, 51-85082

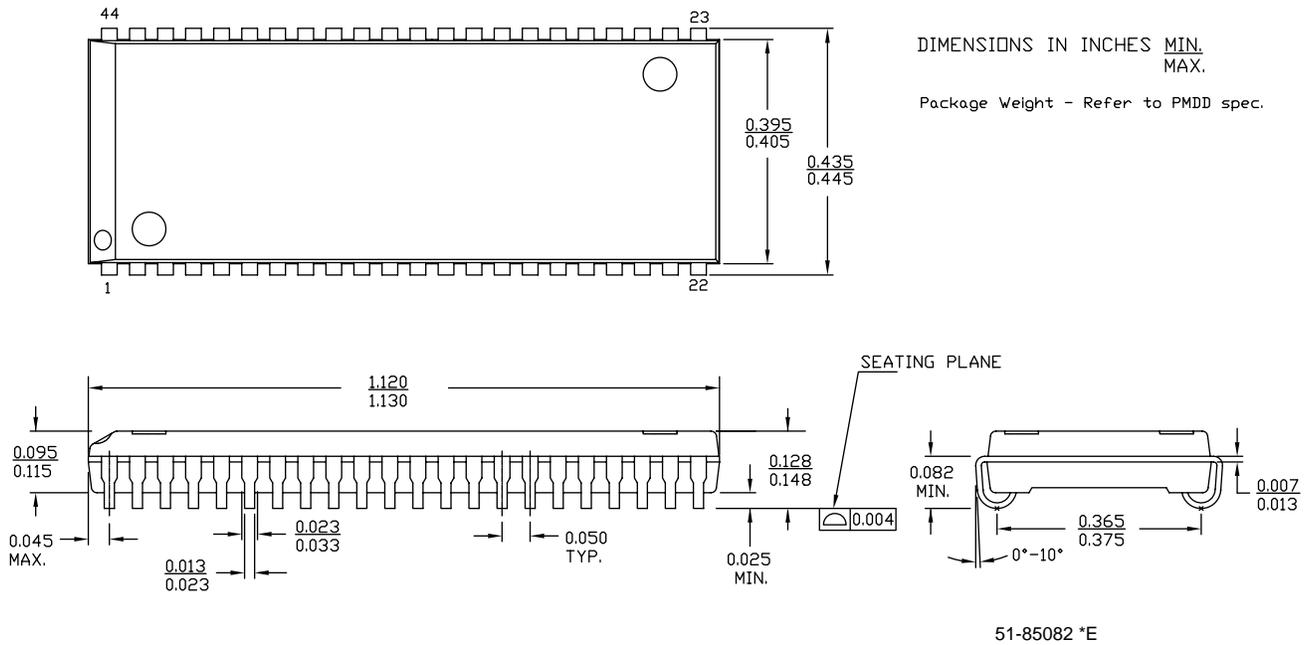
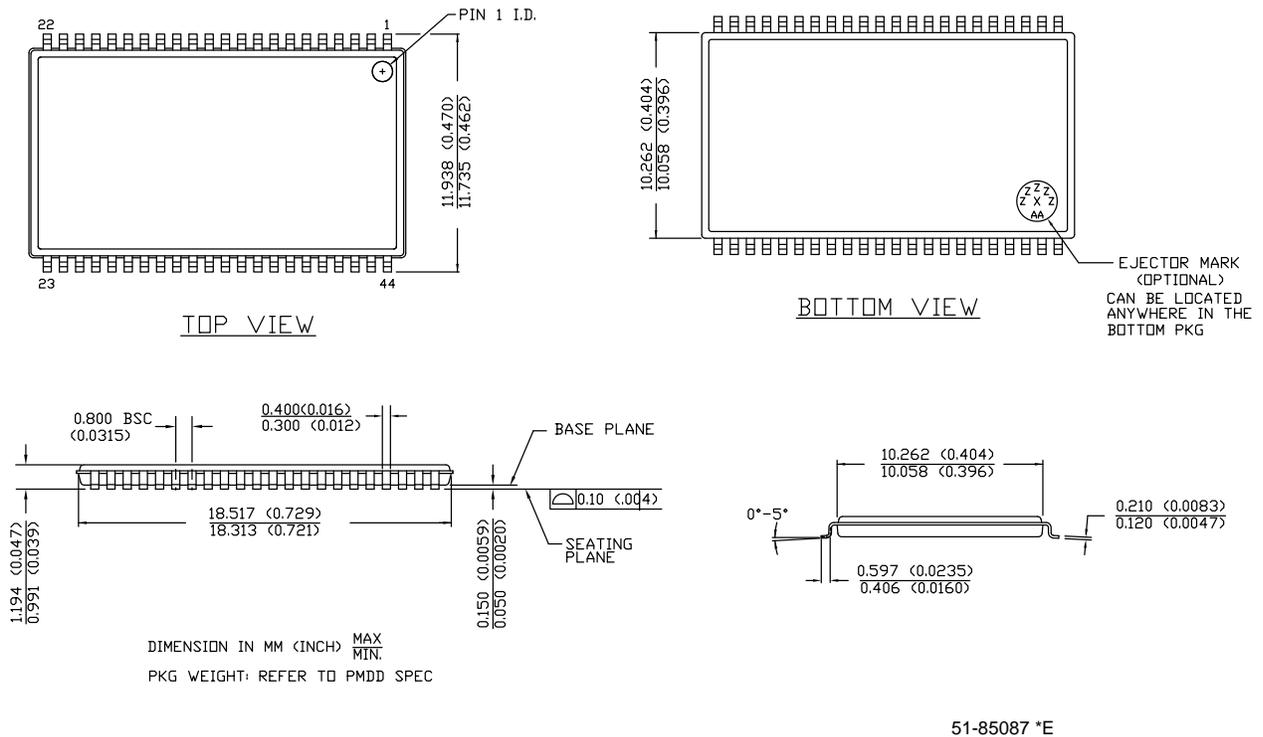
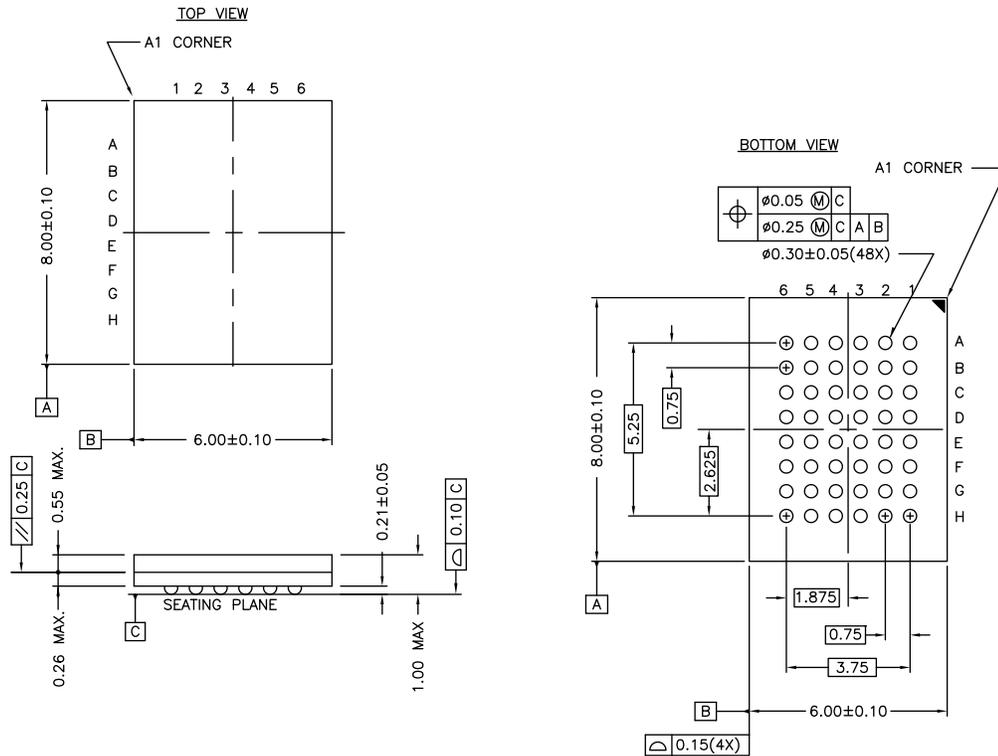


Figure 9. 44-pin TSOP Z44-II Package Outline, 51-85087



Package Diagrams (continued)

Figure 10. 48-ball VFBGA (6 × 8 × 1.0 mm) BV48/BZ48 Package Outline, 51-85150



NOTE:
 PACKAGE WEIGHT: See Cypress Package Material Declaration Datasheet (PMDD) posted on the Cypress web.

51-85150 *H

Acronyms

Acronym	Description
$\overline{\text{BHE}}$	Byte High Enable
$\overline{\text{BLE}}$	Byte Low Enable
CMOS	Complementary Metal Oxide Semiconductor
$\overline{\text{CE}}$	Chip Enable
I/O	Input/Output
$\overline{\text{OE}}$	Output Enable
SOJ	Small-Outline J-leaded
SRAM	Static Random Access Memory
TSOP	Thin Small-Outline Package
TTL	Transistor-Transistor Logic
VFBGA	Very Fine-Pitch Ball Grid Array
$\overline{\text{WE}}$	Write Enable

Document Conventions

Units of Measure

Symbol	Unit of Measure
°C	degree Celsius
MHz	megahertz
μA	microampere
μs	microsecond
mA	milliampere
ns	nanosecond
%	percent
pF	picofarad
V	volt
W	watt

Document History Page

Document Title: CY7C1021DV33, 1-Mbit (64 K × 16) Static RAM Document Number: 38-05460				
Rev.	ECN No.	Issue Date	Orig. of Change	Description of Change
**	201560	See ECN	SWI	Advance Information data sheet for C9 IPP.
*A	233693	See ECN	RKF	Updated Electrical Characteristics (modified as per Eros (Spec # 01-02165)). Updated Ordering Information (included Pb-free offering).
*B	263769	See ECN	RKF	Updated Functional Description (Changed I/O ₁ –I/O ₁₆ to I/O ₀ –I/O ₁₅). Updated Pin Configurations (Changed I/O ₁ –I/O ₁₆ to I/O ₀ –I/O ₁₅). Added Data Retention Characteristics and Data Retention Waveform . Updated Switching Characteristics (Added T _{power} parameter and its details). Updated Ordering Information (Added shade, no change in part numbers).
*C	307601	See ECN	RKF	Updated Selection Guide (Reduced Speed bins to -8 and -10 ns (Removed -12 and -15 speed bins related information)). Updated Electrical Characteristics (Reduced Speed bins to -8 and -10 ns (Removed -12 and -15 speed bins related information)). Updated Switching Characteristics (Reduced Speed bins to -8 and -10 ns (Removed -12 and -15 speed bins related information)). Updated Ordering Information (Updated part numbers).
*D	520652	See ECN	VKN	Changed status from Preliminary to Final. Updated Features (Removed Commercial Operating range related information and included Automotive-A, Automotive-E Operating range related information). Updated Selection Guide (Removed -8 speed bin related information and included -12 speed bin related information). Updated Operating Range (Removed Commercial Operating range related information and included Automotive-A, Automotive-E Operating range related information). Updated Electrical Characteristics (Updated DC Electrical Characteristics (Removed -8 speed bin related information and included -12 speed bin related information, removed Commercial Operating range related information and included Automotive-A, Automotive-E Operating range related information), Updated Note 2 (Changed V _{IH(max)} from V _{CC} + 2 V to V _{CC} + 1 V), added I _{CC} parameter values for the frequencies 83 MHz, 66 MHz and 40 MHz). Updated Thermal Resistance (Replaced TBD with values for all packages). Updated Switching Characteristics (Removed -8 speed bin related information and included -12 speed bin related information, removed Commercial Operating range related information and included Automotive-A, Automotive-E Operating range related information). Updated Data Retention Characteristics (Removed Commercial Operating range related information and included Automotive-A, Automotive-E Operating range related information). Updated Ordering Information (Updated part numbers).
*E	2898399	03/24/2010	AJU	Updated Package Diagrams .
*F	3109897	12/14/2010	AJU	Added Ordering Code Definitions . Updated Package Diagrams .

Document History Page (continued)

Document Title: CY7C1021DV33, 1-Mbit (64 K × 16) Static RAM				
Document Number: 38-05460				
Rev.	ECN No.	Issue Date	Orig. of Change	Description of Change
*G	3421856	10/25/2011	TAVA	<p>Updated Features (Removed Automotive-E Operating range related information).</p> <p>Updated Selection Guide (Removed Automotive-E Operating range related information, removed -12 speed bin related information).</p> <p>Updated Operating Range (Removed Automotive-E Operating range related information, removed -12 speed bin related information).</p> <p>Updated Electrical Characteristics (Updated DC Electrical Characteristics (Removed Automotive-E Operating range related information, removed -12 speed bin related information)).</p> <p>Updated Switching Characteristics (Removed Automotive-E Operating range related information, removed -12 speed bin related information).</p> <p>Updated Data Retention Characteristics (Removed Automotive-E Operating range related information).</p> <p>Updated Switching Waveforms.</p> <p>Updated Ordering Information (Updated part numbers).</p> <p>Updated Package Diagrams.</p> <p>Updated to new template.</p>
*H	4578364	11/24/2014	MEMJ	<p>Updated Functional Description: Added "For a complete list of related resources, click here." at the end.</p> <p>Updated Switching Characteristics: Added Note 13 and referred the same note in "Write Cycle".</p> <p>Updated Switching Waveforms: Added Note 19 and referred the same note in Figure 7.</p> <p>Updated Ordering Information (Removed shade, no change in part numbers).</p> <p>Updated Package Diagrams: spec 51-85082 – Changed revision from *D to *E. spec 51-85087 – Changed revision from *D to *E. spec 51-85150 – Changed revision from *G to *H.</p> <p>Added Acronyms and Units of Measure.</p> <p>Updated to new template.</p> <p>Completing Sunset Review.</p>

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